

To: Technology Unit: 3744
Facsimile Number: 703-872-9306


Total Pages Sent 12

From: W. Daniel Swayze, Jr.
Texas Instruments Incorporated
Facsimile: 972-917-4418
Phone: 972-917-5633

RECEIVED
CENTRAL FAX CENTER

JUN 21 2005

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

CERTIFICATION OF FACSIMILE TRANSMISSION	
I hereby certify that the following papers are being transmitted by facsimile to the U.S. Patent and Trademark Office at 703-872-9306 on the date shown below:	
 Tommie Chambers	<u>6-21-05</u> Date

FACSIMILE COVER SHEET

<input checked="" type="checkbox"/> FACSIMILE COVER SHEET <input type="checkbox"/> NEW APPLICATION <input type="checkbox"/> DECLARATION (# Pages) <input type="checkbox"/> ASSIGNMENT (# Pages) <input type="checkbox"/> FORMAL DRAWINGS <input type="checkbox"/> INFORMAL DRAWINGS <input type="checkbox"/> CONTINUATION APP'N (# Pages) <input type="checkbox"/> DIVISIONAL APP'N	<input checked="" type="checkbox"/> AMENDMENT (10 Pages) <input checked="" type="checkbox"/> EOT (1 Month) <input type="checkbox"/> NOTICE OF APPEAL <input type="checkbox"/> APPEAL (# Pages) <input type="checkbox"/> ISSUE FEE (# Pages) <input type="checkbox"/> CHANGE IN CORRESPONDENCE <input type="checkbox"/> ADDRESS
NAME OF INVENTOR(S): Sheperck	RECEIPT DATE & SERIAL NO.: Serial No.: 10/736,661 Filing Date: 12/16/2003
TITLE OF INVENTION: TEMPERATURE COMPENSATION SYSTEMS AND METHODS FOR USE WITH READ/WRITE HEADS IN MAGNETIC STORAGE DEVICES	
TI FILE NO.: TI-36723	DEPOSIT ACCT. NO.: 20-0668
FAXED: <u>6-21-05</u> DUE: 05/24/2005 ATTY/SEC'Y: WDS/tlc	

This facsimile is intended only for the use of the address named and contains legally privileged and/or confidential information. If you are not the intended recipient of this telecopy, you are hereby notified that any dissemination, distribution, copying or use of this communication is strictly prohibited. Applicable privileges are not waived by virtue of the document having been transmitted by Facsimile. Any misdirected facsimiles should be returned to the sender by mail at the address indicated on this cover sheet.

Texas Instruments Incorporated
PO Box 655474, M/S 3999
Dallas, TX 75265

RECEIVED
OIPE/IAP

JUN 22 2005